MECHANICAL DATA



D. The package thermal pad must be soldered to the board for thermal and mechanical performance.

- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- earrow Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated.
- The Pin 1 identifiers are either a molded, marked, or metal feature.
- G. Package complies to JEDEC MO-241 variation BA.



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